



#### **Features**

• Transient protection for high-speed data lines IEC 61000-4-2 (ESD) ±15kV (Air)

±8kV (Contact)

IEC 61000-4-4 (EFT) 40A (5/50 ns) Cable Discharge Event (CDE)

- Package optimized for high-speed lines
- Ultra-small package (2.5mm× 1.0mm× 0.55mm)
- Protects four data lines
- Ultra Low capacitance: 0.6pF for each channel
- Low leakage current: 0.1µA @ V<sub>RWM</sub> (Typical)
- Low clamping voltage
- Each I/O pin can withstand over 1000 ESD strikes for ±8kV contact discharge
- Pb free & RoHS Compliant

#### **Applications**

- Serial ATA
- PCI Express
- Desktops, Servers and Notebooks
- MDDI Ports
- USB2.0 Power and Data Line Protection
- Display Ports
- High Definition Multi-Media Interface (HDMI)
- Digital Visual Interfaces (DVI)

#### **Mechanical Characteristics**

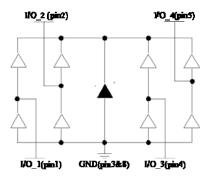
- DFN-10L package
- Flammability Rating: UL 94V-0
- Marking: Part numbe, Date
- Packaging: Tape and Reel

## **General Description**

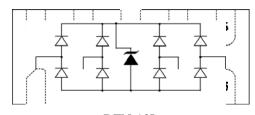
#### 旨在保护寄生敏感系统免受 过压和过流瞬态事件 Circuit Diagram

CS0806S is an ultra-low capacitance Transient Voltage Suppressor (TVS) designed to provide electrostatic discharge (ESD) protection for high-speed data interfaces. With typical capacitance of 0.6pF only, CS0806S is designed to protect parasitic-sensitive systems against over-voltage and over-current transient events. It complies with IEC 61000-4-2 (ESD), Level 4 (±15kV air, ±8kV contact discharge), IEC 61000-4-4 (electrical fast transient -EFT) (40A, 5/50 ns), very fast charged device model (CDM) ESD and cable discharge event (CDE), etc.

CS0806S uses ultra-small DFN-10L package. Each CS0806S device can protect four high-speed data lines. The combined features of ultra-low capacitance, ultra-small size and high ESD robustness make CS0806S deal for high-speed data ports and high-frequency lines (e.g., HDMI & DVI) applications. The low clamping voltage of the CS0806S guarantees a minimum stress on the protected IC.



## **Pin Configuration**



DFN-10L (Top View)

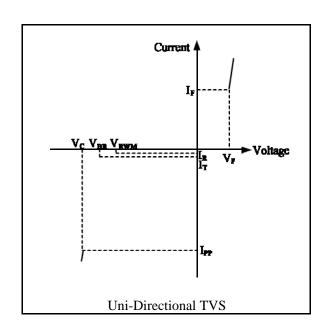
别称: DFN2510-10L DFN2510-10 SOT1165-1

## **Absolute Maximum Rating**

Symbol	Parameter	Value	Units
V	ESD per IEC 61000-4-2 (Air)	±17	
ESD	ESD per IEC 61000-4-2 (Contact)	±12	kV
I OPT	Operating Temperature	-55/+125	° C
STG	Storage Temperature	-55/+150	° C

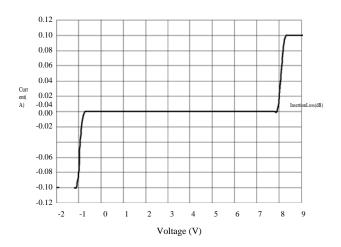
## **Electrical Characteristics (T = 25° C)**

Symbol	Parameter			
V RWM	Nominal Reverse Working Voltage			
$I_R$	Reverse Leakage Current @ V <sub>RWM</sub>			
V BR	Reverse Breakdown Voltage @ I <sub>T</sub>			
$I_{\mathrm{T}}$	Test Current for Reverse Breakdown			
$V_{\rm C}$	Clamping Voltage @ I <sub>PP</sub>			
I PP	Maximum Peak Pulse Current			
ESD	Parasitic Capacitance			
$V_{R}$	Reverse Voltage			
f	Small Signal Frequency			
$I_{\mathrm{F}}$	Forward Current			
$V_{\mathrm{F}}$	Forward Voltage @ I <sub>F</sub>			

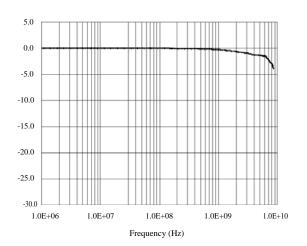


Symbol	Test Co dition	Minimum	Typical	Maximum	Units
V				<b>~</b> 0	**
RWM		<b>!</b>		5.0	V
$I_R$	V <sub>RWM</sub> = 5V, T = 25° C Between I/O and GND		0.1	1.0	μΑ
V BR	I <sub>T</sub> = 1mA Between I/O and GND	6.0	8.0	10.0	V
$V_{\mathrm{C}}$	I <sub>PP</sub> = 1A, t <sub>p</sub> = 8/20μs Between I/O and GND			12	V
C esd	V <sub>R</sub> = 0V, f = 1MHz Between I/O and GND		0.6	0.8	pF
ESD	$V_R = 0V$ , $V_{pin3,8} = 0V$ , $f = 1MHz$ Between I/O and I/O		0.05	0.08	pF

## Voltage Sweeping of I/O to GND

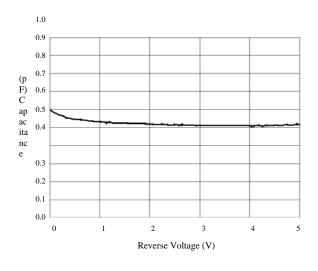


## **Insertion Loss S21 of I/O to GND**

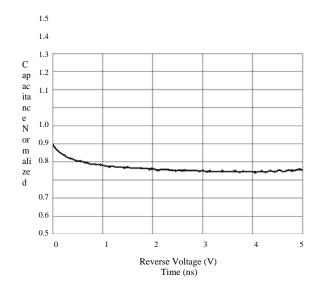


## Capacitance vs. Voltage of I/O to GND (f = 1MHz)

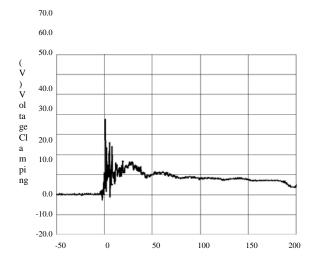
Capacitance vs. Reverse Voltage



Normalized Capacitance vs. Reverse Voltage

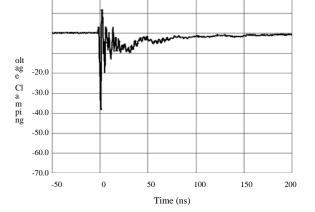


### ESD Clamping of I/O to GND (+8kV Contact per IEC 61000-4-2)



# ESD Clamping of I/O to GND (-8kV Contact per IEC 61000-4-2)





CS0806S Rev.0.9

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#### **Application Information**

#### **Pin Connection in PCB**

CS0806S provides ESD protection for four data lines simultaneously. The pin connection is shown in the figure below.

Four parallel data lines, from inner IC to I/O port connector, could connect to CS0806S four I/O pins directly. Pin 3&8 of CS0806S is the GND pin, which should connect to the GND of PCB. The wire should be as short as possible in order to minimize the parasitic inductance.

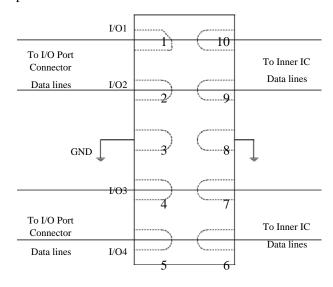


Figure 1 CS0806S pin connection in PCB

#### **PCB Layout Guidelines**

For optimum ESD protection and the whole circuit performance, the following PCB layout guidelines are recommended:

- CS0806S GND pin to the PCB GND rail path should be as short as possible. It could reduce the ESD transient return path to GND.
- The vias connecting CS0806S GND pins to the PCB GND should be wide.
- Place CS0806S as close to the connector port as possible. It could reduce the parasitic inductance and restrict ESD coupling into adjacent traces.
- Avoid running critical signals near board edges.



## **Application Information**

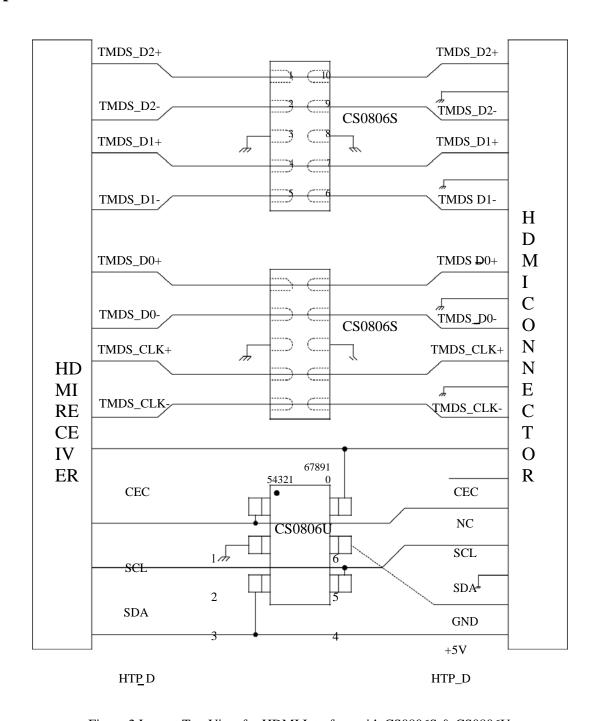
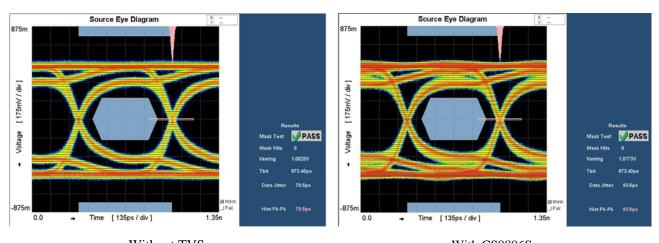


Figure 2 Layout Top View for HDMI Interface with CS0806S & CS0806U



#### **Application Information**

#### Eye Diagram Measurements for 1080P HDMI Data Transmission



Without TVS With CS0806S

Figure 3 Eye Diagram Measurements for 1080P HDMI

#### **TDR Measurements for HDMI**

The combination of low capacitance, small package, and flow-th ough design means it is possible to use CS0806S to meet the HDMI impedance requirements of 100 Ohms  $\pm 15\%$ . Figures 4 shows impedance test result for a TDR rise time of 100ps, using a CitrusCom evaluation bo rd with 100 Ohm differential traces. Measurements were taken using a TDR method as outlined in the HDMI Compliance Test Specification (CTS). In this case, the device meets the HDMI CTS requirement of 100 Ohm  $\pm 15\%$  with plenty of margin.

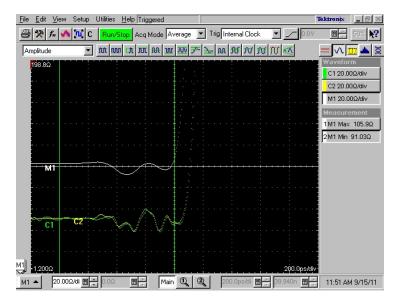
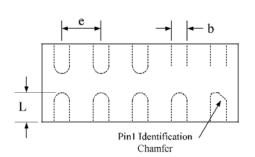


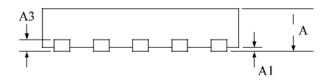
Figure 4 TDR Measurements for HDMI



## **Package Outline**

- DFN-10L package
- Thermally-Enhanced
- MSL-1 Level



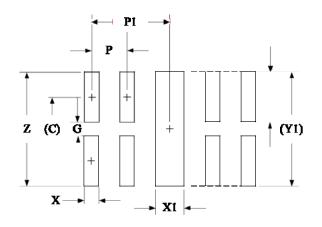


Package Dimensions (Controlling dimensions are in millimeters)

C	Dimensio	os (mm)	Dimensions (Inches)		
Symbol	Minimum Maximum		Minimum	Maximum	
A	0.500	0.600	0.020	0.024	
A1	0.000	0.050	0.000	0.002	
A3	0.15	REF.	0.006REF.		
b	0.150	0.250	0.006	0.010	
D	2.450	2.550	0.096	0.100	
Е	0.950	1.050	0.037	0.041	
e	0.500 BSC		0.020 BSC		
L	0.300	0.400	0.012	0.016	

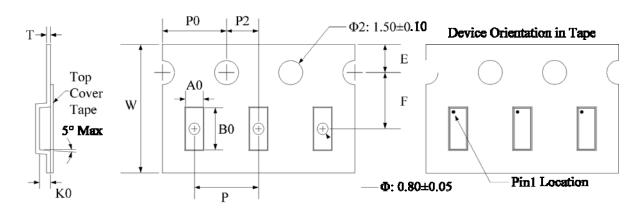


## **PCB Layout Pattern**



DIMENSIONS					
DIM	INCHES	MILLIMETERS			
С	(0.034)	(0.875)			
G	0.008	0.20			
P	0.020	0.50			
P1	0.039	1.00			
X	0.008	0.20			
X1	0.016	0.40			
Y	0.027	0.675			
Y1	(0.061)	(1.55)			
Z	0.061	1.55			

## **Tape and Reel Specification**



Symbol	W	A0	В0	K0	Е	F	P	P0	P2	Т
Dimensions	8.00+0.3									
(mm)	-0.1	1.23±0.05	2.7±0.05	0.7±0.05	1.75±0.1	3.5±0.05	4.0±0.1	4.0±0.1	2.0±0.05	0.25±0.02

## **Marking Codes**



## **Ordering Information**

Part Number	Working Voltage	Quantity Per Reel	Reel Size	
CS0806S	5V	3,000	7 Inch	

#### Note:

(1) "6S" is part number, while "YWW" is date code.